eBOX671-521-FL
Fanless Embedded System with LGA1151 9th/8th Gen Intel® Core™ i7/i5/i3 & Celeron® Processors, 4-CH PoE and MXM 3.1 Type A

Features
- 9th/8th gen Intel® Core™ i7/i5/i3 & Celeron® with Intel® Q370 chipset (Coffee Lake/Coffee Lake Refresh-S)
- 4-CH PoE (IEEE802.3at compliance)
- Dual swappable 2.5" SATA HDD drive bay with RAID 0 & 1
- Supports MXM 3.1 type A graphics module (optional)
- DVI-I, HDMI, and DisplayPort with triple-view supported
- AMS.AXView 3.0 intelligent remote monitoring software for IIoT

Specifications
- **Standard Color** Silver
- **Construction** Aluminum extrusion and heavy-duty steel, IP40
- **CPU** LGA1151 9th/8th gen Intel® Core™ i7/i5/i3 & Celeron® processors (35W/65W)
- **System Memory** 2 x 260-pin DDR4-2666 SO-DIMM, up to 64GB (ECC supported by Intel® C246 PCH)
- **Chipset** Intel® Q370/optional Intel® C246 PCH
- **BIOS** AMI
- **System I/O Outlet**
  - 1 x internal MXM3.1 Type A connector
  - 2 x SIM slot
  - 1 x mSATA supported
- **Power Input** 24 VDC

**Watchdog Timer**
255 levels, 1 to 255 sec.

**Storage**
2 x 2.5" HDD drive bay (max. up 9.5 mm height)
1 x mSATA (enabled in BIOS setting)

**Expansion Interface**
2 x full-size PCI Express Mini Card slot (USB + PCIe signal)
2 x SIM slot
1 x internal mMXM3.1 type A connector

**TPM**
TPM 2.0

**System Indicator**
1 x Green LED for system power-on
1 x Green LED for HDD active
4 x Green LED for programmable

**Power Input**
24 VDC

**Operating Temperature**
Without MXM module:
-40°C to 60°C (-40°F to +140°F) (with W.T. DRAM & SSD, CPU TDP 35W)
-40°C to 50°C (-40°F to +122°F) (with W.T. DRAM & SSD, CPU TDP 65W)
With MXM module:
-40°C to 50°C (-40°F to +122°F) (with W.T. DRAM & SSD & MXM kit, CPU TDP 35W)

**Humidity**
10% ~ 90%, non-condensing

**Shock Vibration**
IEC 60068-2-27 (w/ SSD: 50G@wall mount, half-sine, 11 ms duration)

**Vibration Endurance**
IEC 60068-2-64 (w/ SSD: 30ms Strd, random, 5 - 500 Hz, 1 Hz/axis)
Dimensions:
280 mm (11.02") x 210 mm (8.26") x 80.5 mm (3.16") (H)
Weight (net/gross):
4.8 kg (10.58 lb)/6.6 kg (12.34 lb)

**Certifications**
CE, FCC Class A

**Power Protection**
- **DC Version**
  - OVP (over voltage protection)
  - UVP (under voltage protection)
  - QCP (over current protection)
  - SCP (short circuit protection)
- **Software Support**
  - EOS Win 10 IoT, Linux

**Ordering Information**
- **Standard**
  - eBOX671-521-FL-DC-4PoE Fanless embedded system with LGA1151 9th/8th gen Intel® Core™ i7/i5/i3 & Celeron® processor, Intel® Q370, DVI-I, HDMI, dual HDD, 4 PoE, 2 GbE LAN, 6 USB, 2 COM and 24 VDC
  - eBOX671-521-FL-6GbE Fanless embedded system with LGA1151 9th/8th gen Intel® Core™ i7/i5/i3 & Celeron® processor, Intel® Q370, DVI-I, HDMI, dual HDD, 6 GbE LAN, 6 USB, 2 COM and 24 VDC

**Optional**
- 2.5" SATA HDD
- 2.5" SATA SSD
- DDR4 SD-DIMM
- mSATA
- 3G/LTE module
- Wi-Fi module
- 3G/4G LTE module
- MXM 3.1 Type A module

**Dimensions**
- 24V, 120W adapter
- AX92901 LAN PCIe Express Mini module
- AX92903 CAN module with CANopen
- AX92902 LAN PCIe Express Mini module
- 5940392140E RS-232 cable, L=200 mm for COM3/4
- AX92904 DIO PCIe Express Mini module

* Specifications and certifications may vary based on different requirements.

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